

# **Growing Business by the X-ray Lithography**

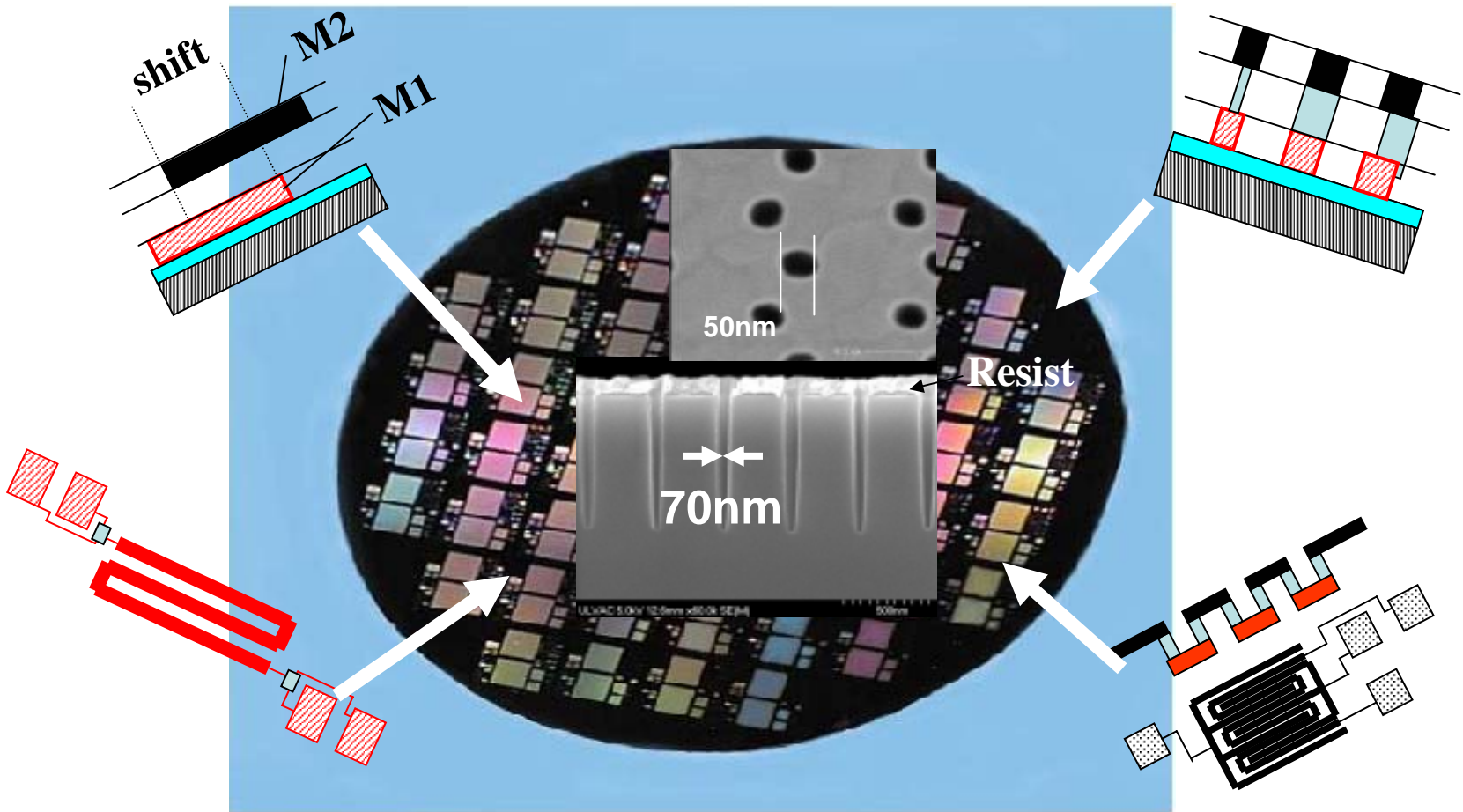
**Yuji Furumura**

Philtech Inc.

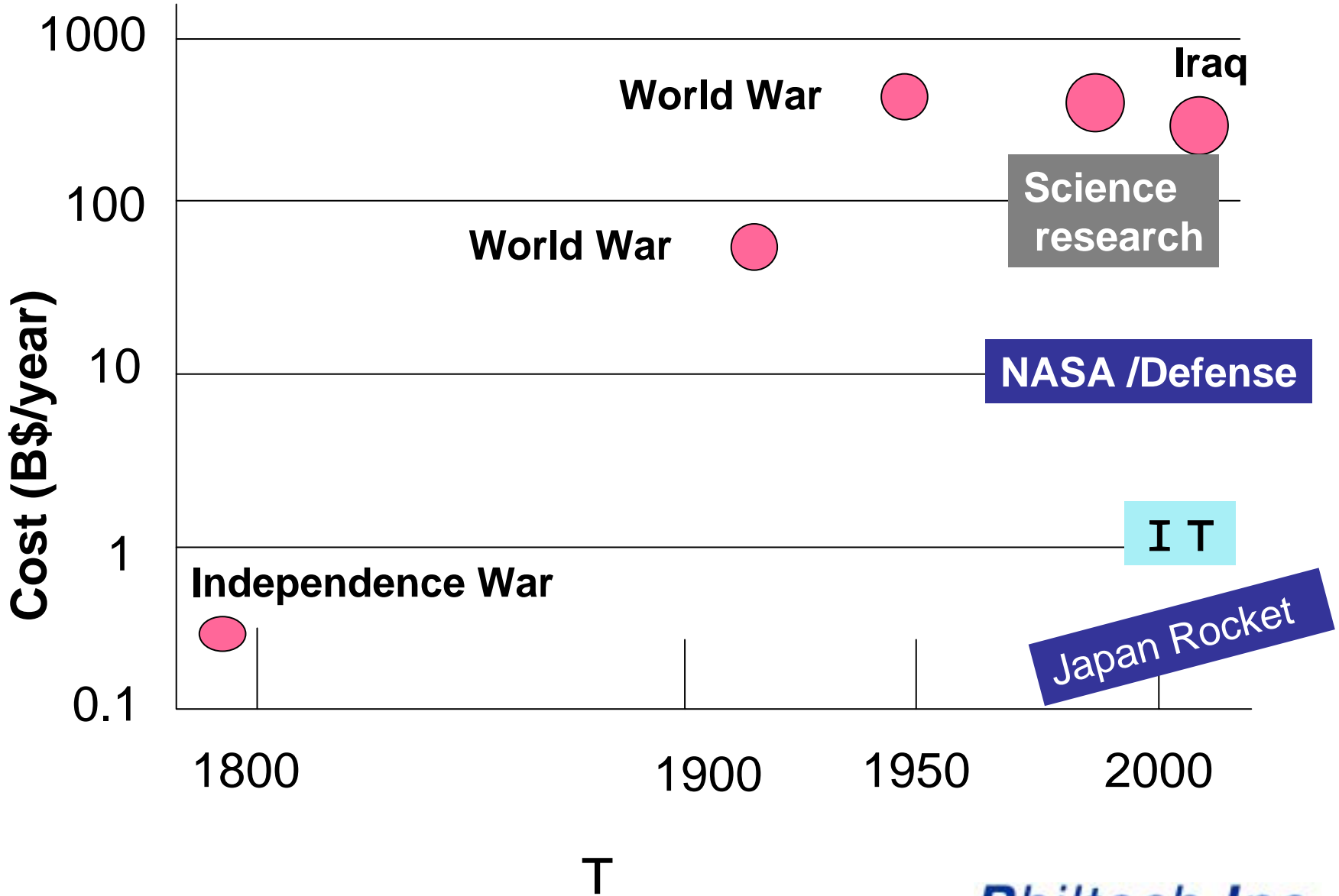
June 29, 2004

NGL 2004

# nm-Patterns on 300mm



*Philtech Inc.*



# Application of X-ray

**US : 100GHz Wave for defense**

**Japan : M E M S , Test wafers,**

**Probe Card, PZT device**

**by LIGA( Lithographie,**

**Galvanoformung, Abformung)**

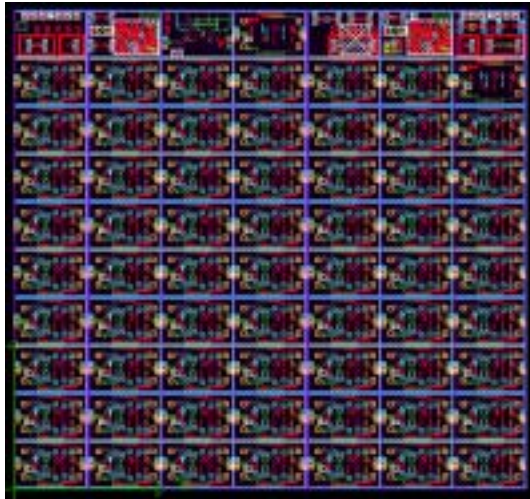
# 70 nm Device Demonstration



**BAE SYSTEMS**

DMS227

DMS187



**90-100 GHz  
missile seeker**

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# Contributers to X-ray lithography



Tohoku U.

Waseda U.



MIT

Grenon Consulting, Inc.



*Philtech Inc.*

# **Tools and facilities**

**X-ray : Mitsubishi SR 0.6GeV**

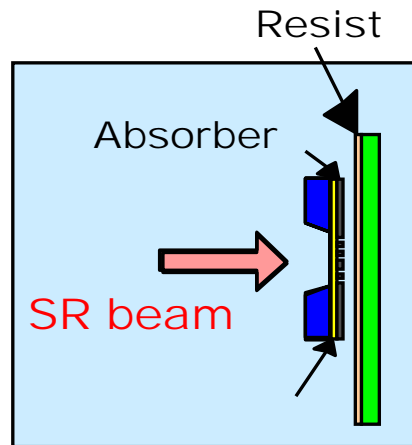
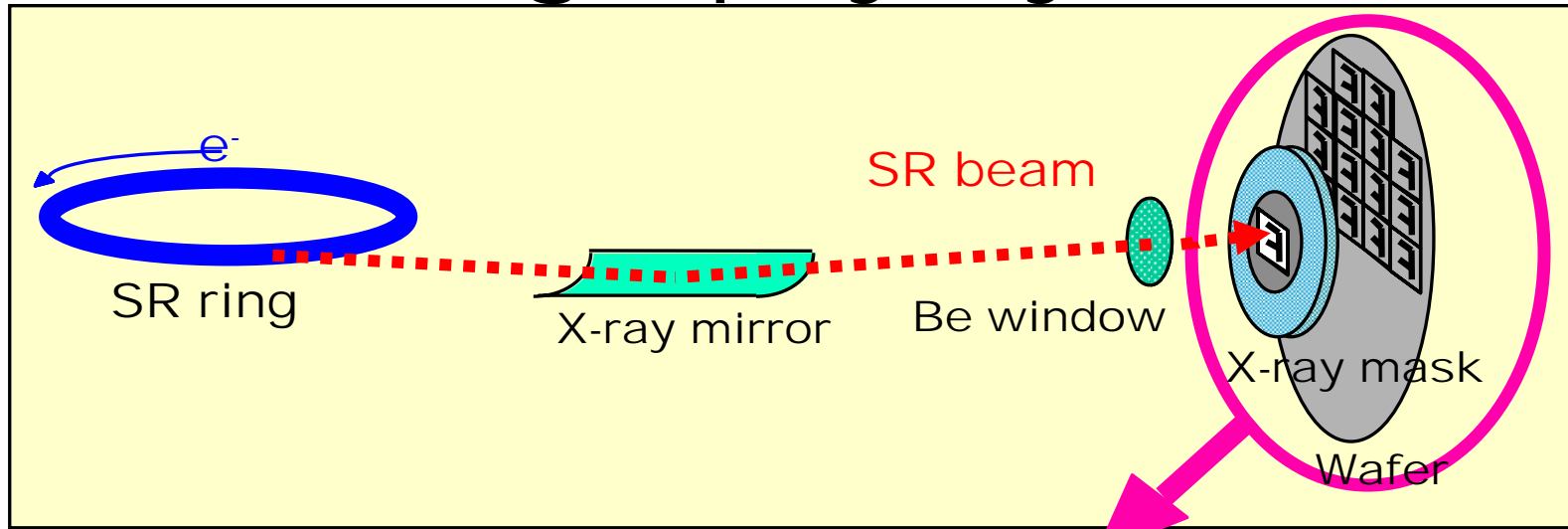
**Stepper : Canon X R A 300mm**

**Coater/Developer:**

**Tokyo Electron A C T 1 2**

**Mask: NTT - A T**

# Lithography System

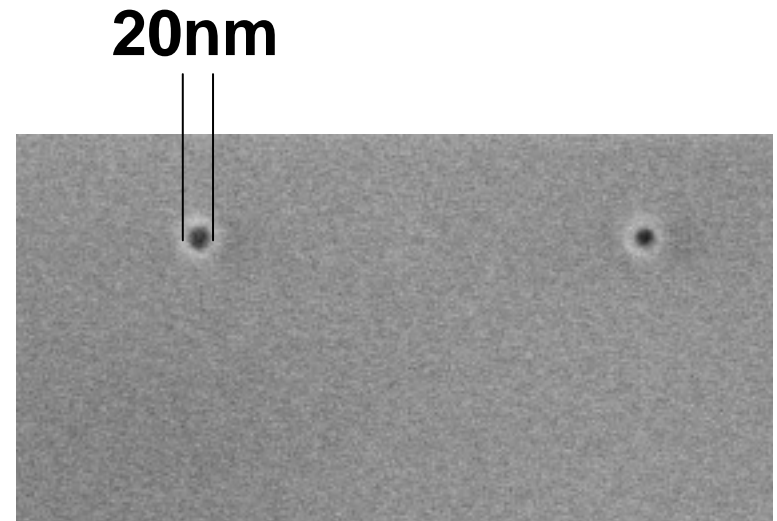
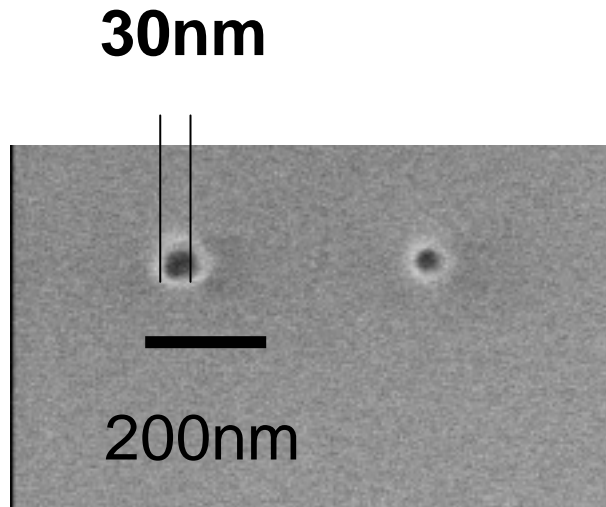


Membrane  
SiC, Diamond

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# Resist patterns on a 300-mm wafer



By Waseda University

*Philtech Inc.*

# **Users of X-ray lithography on 300-mm wafers**

**AMAT**

**Tokyo Electron**

**Ulvac**

**Novellus**

**Ebara**

**Hitachi**

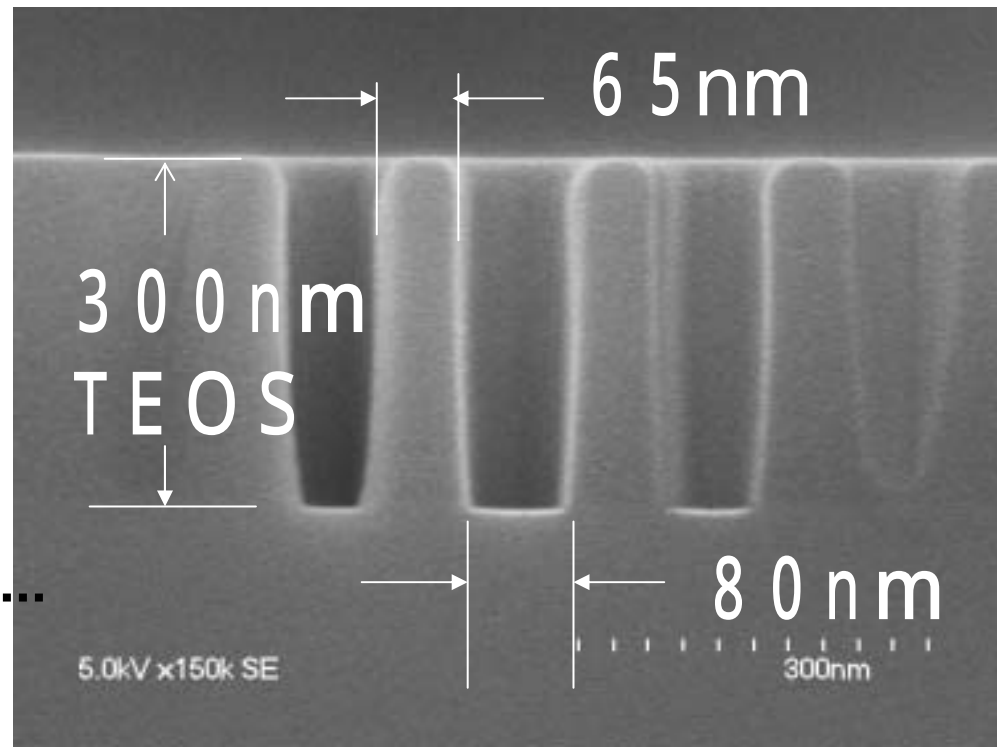
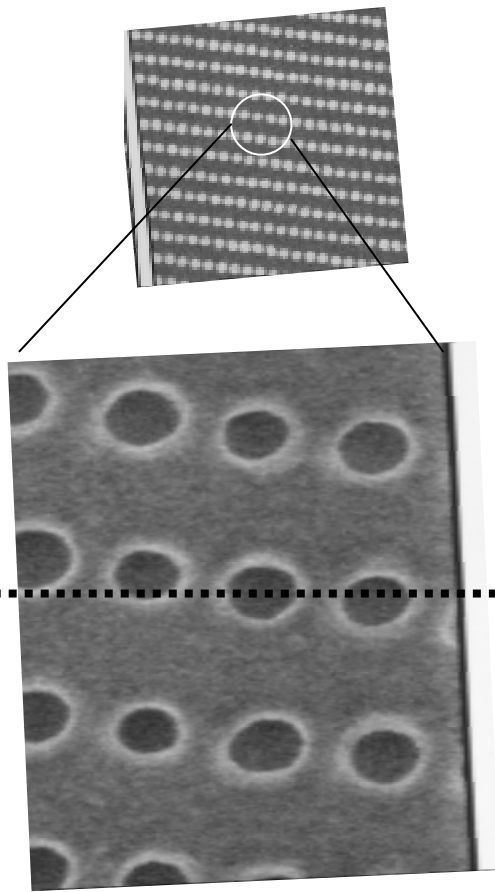
**Universities**

**Others**

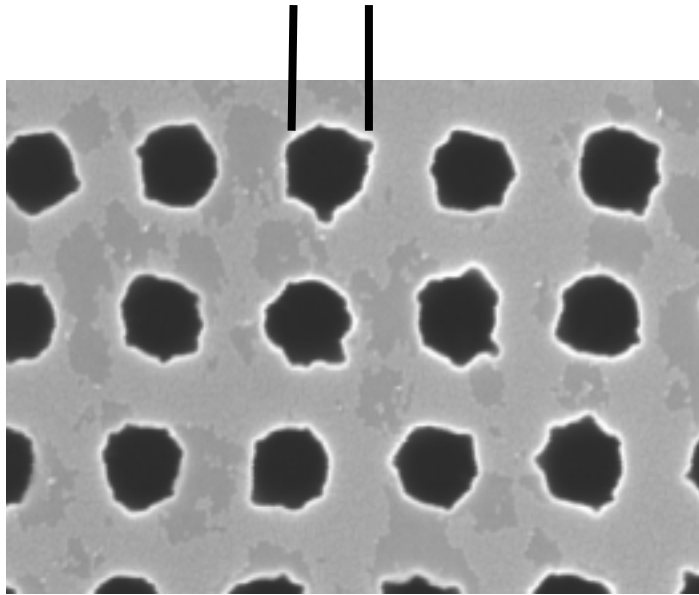
**Why tool makers use?**

**They don't wait for  
Lithography Development  
To win tool market**

# 300mm-wafer with 80nm hole

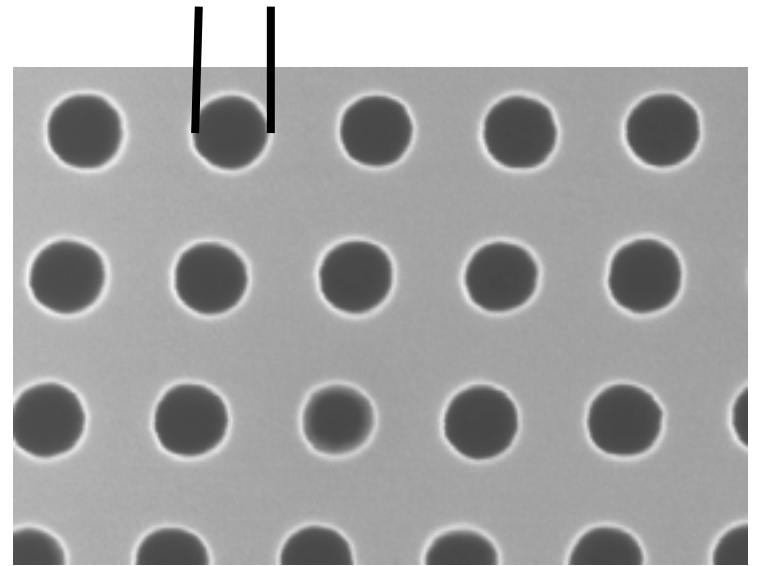


0.12 $\mu$ m



Striation  
Big problem

0.12 $\mu$ m



Striation Solution  
By KrF resist+X-ray

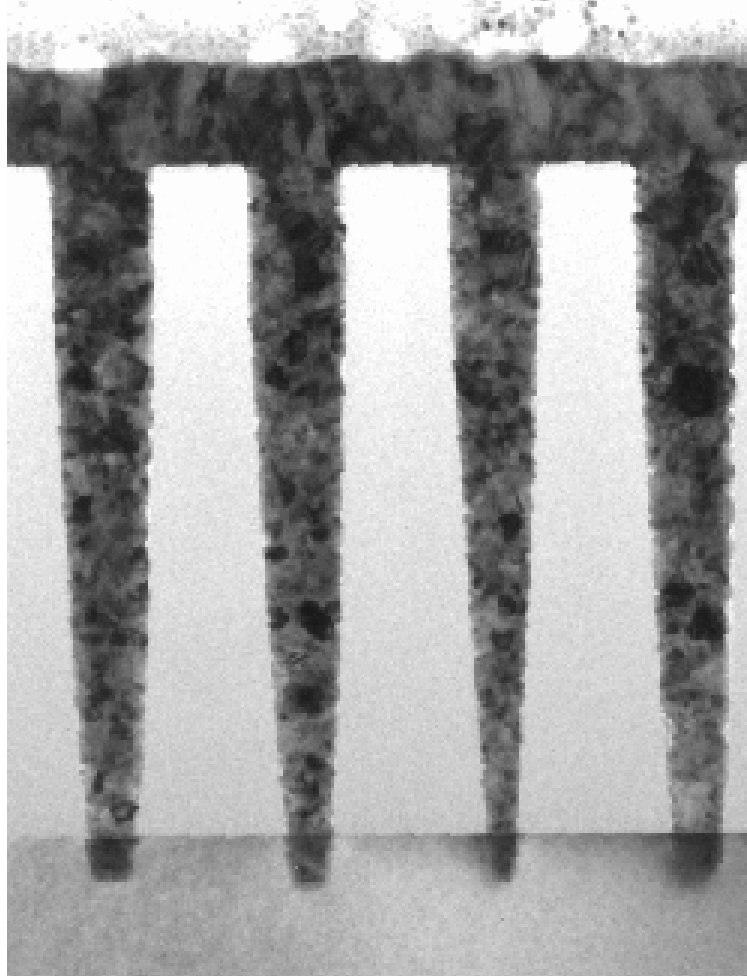
*Philtech Inc.*

# Via Holes filled by Electroless plating

(1 step deposition)

Hiroshima University (IEDM, Dec. 8<sup>th</sup>, 2003)

200nm



Diameter: 100nm

Depth: 950nm

Hole patterns were  
made by X-ray  
lithography

(Philtech Corp.)

No overgrowth

TEM

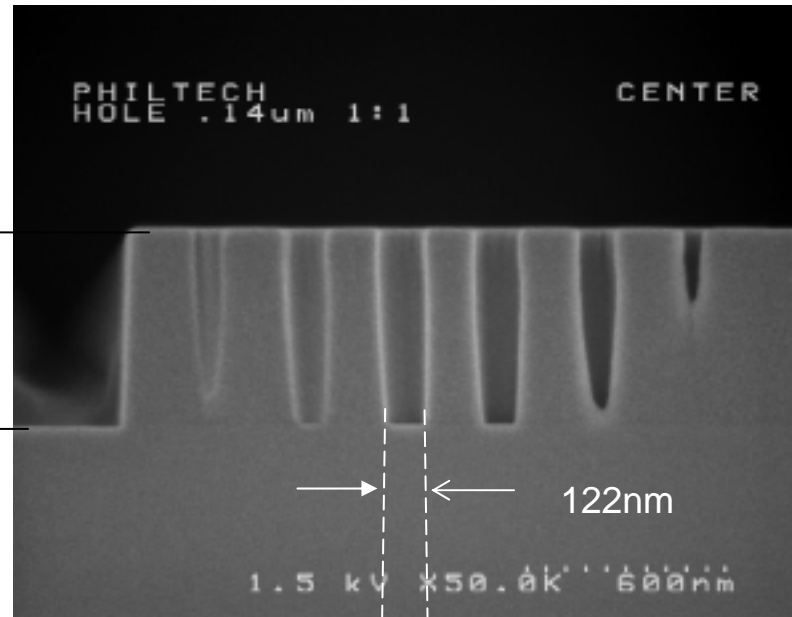
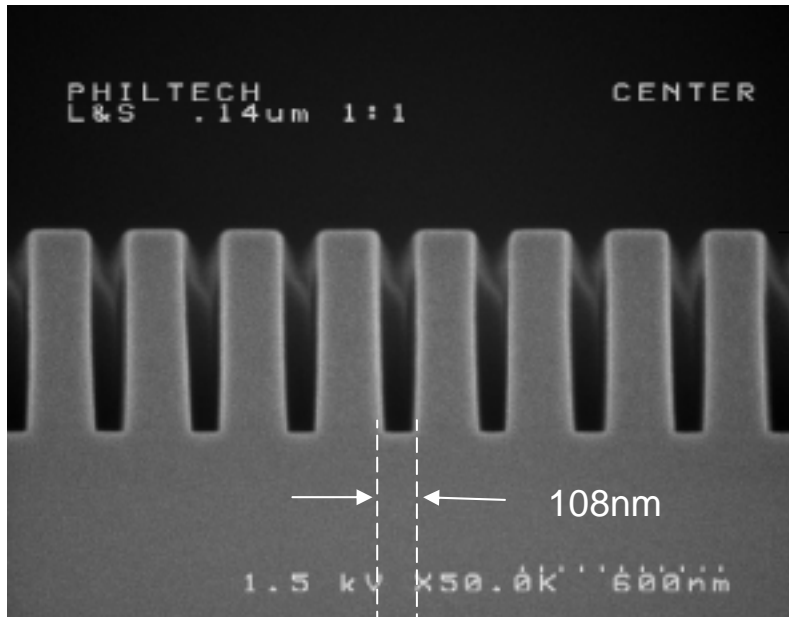
*Philtech Inc.*

# 300mm wafer with 600nm-deep patterns

**Trench**

**dense**

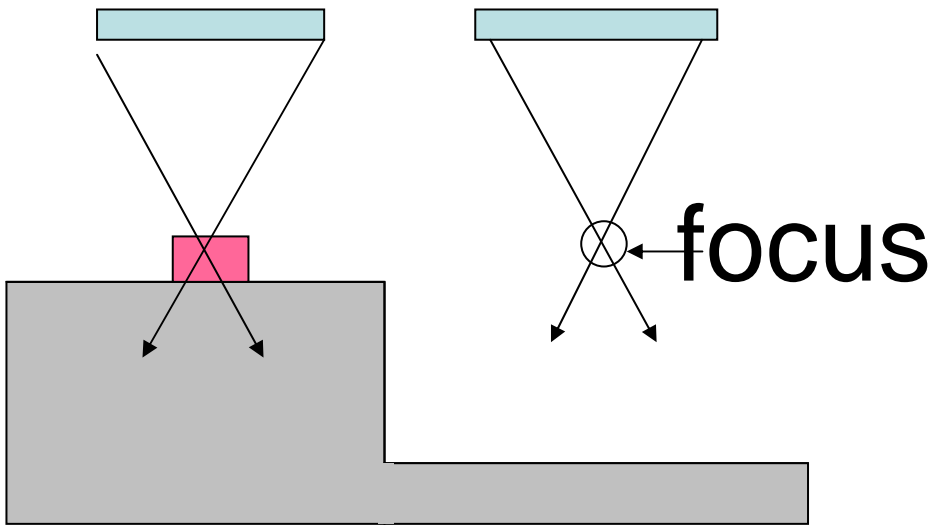
**Hole**



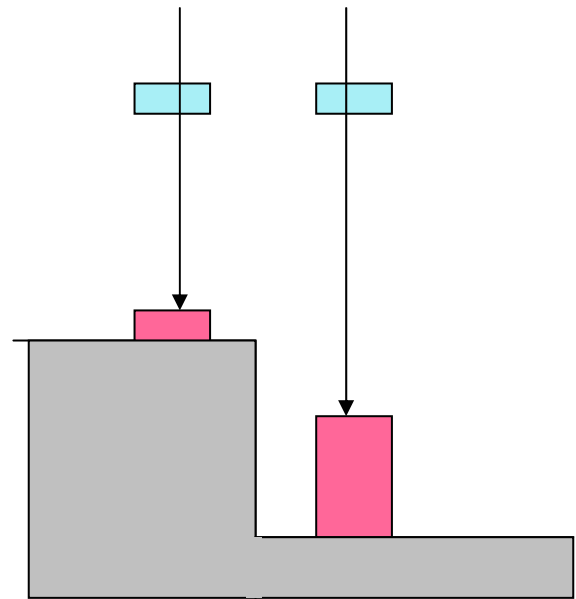
TEOS  
600nm

# Advantage of X-ray litho.

optical

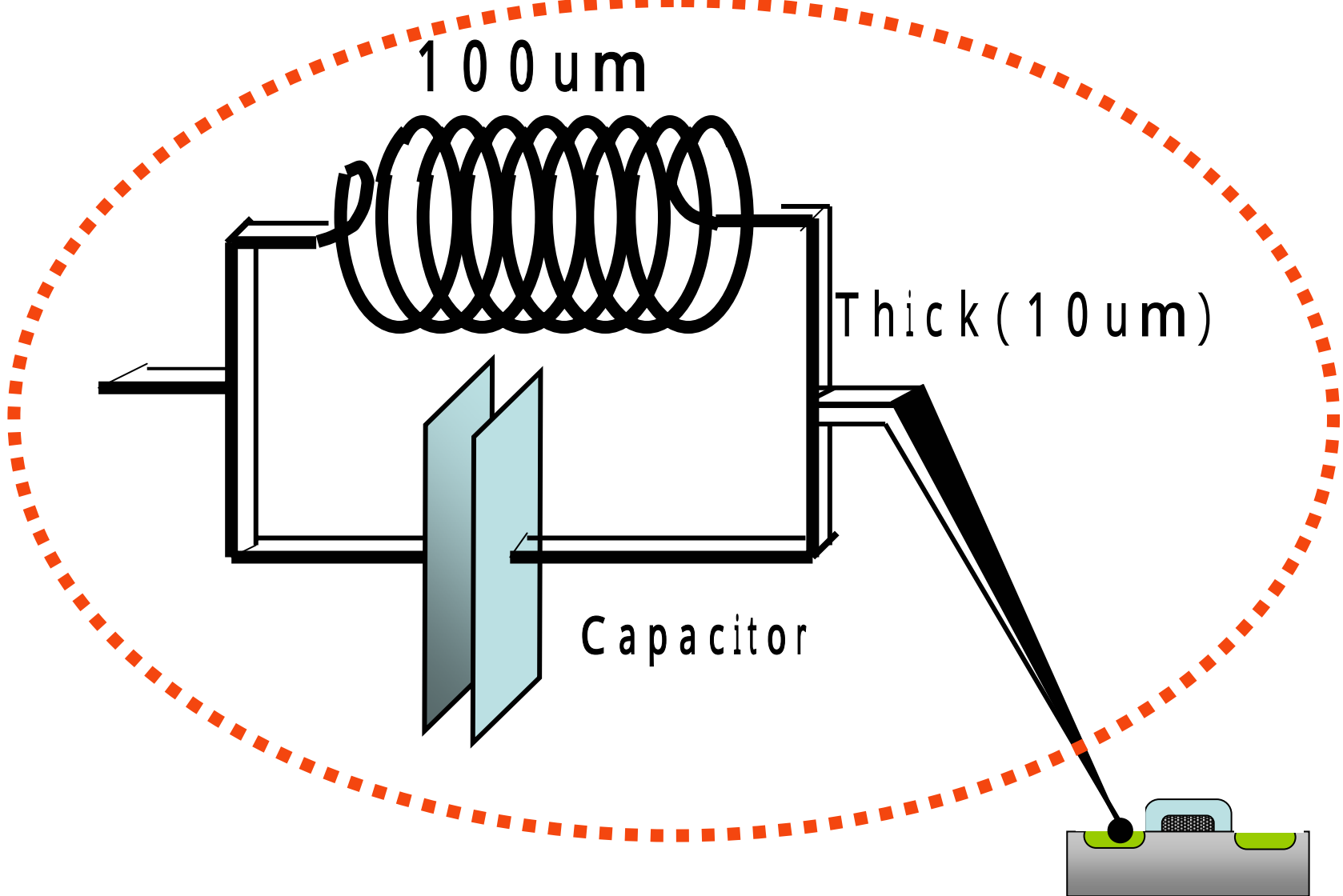


X-ray



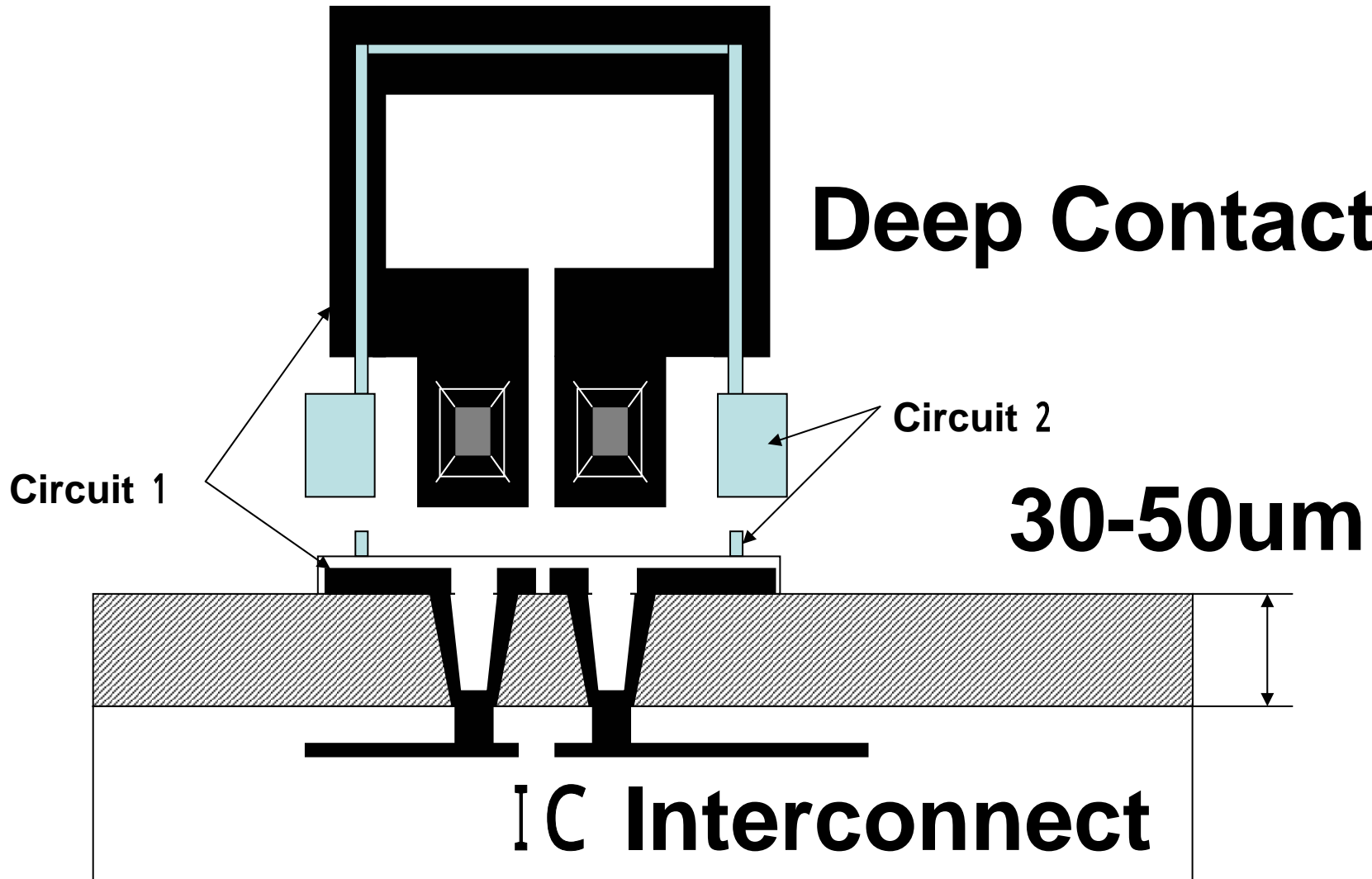
*Philtech Inc.*



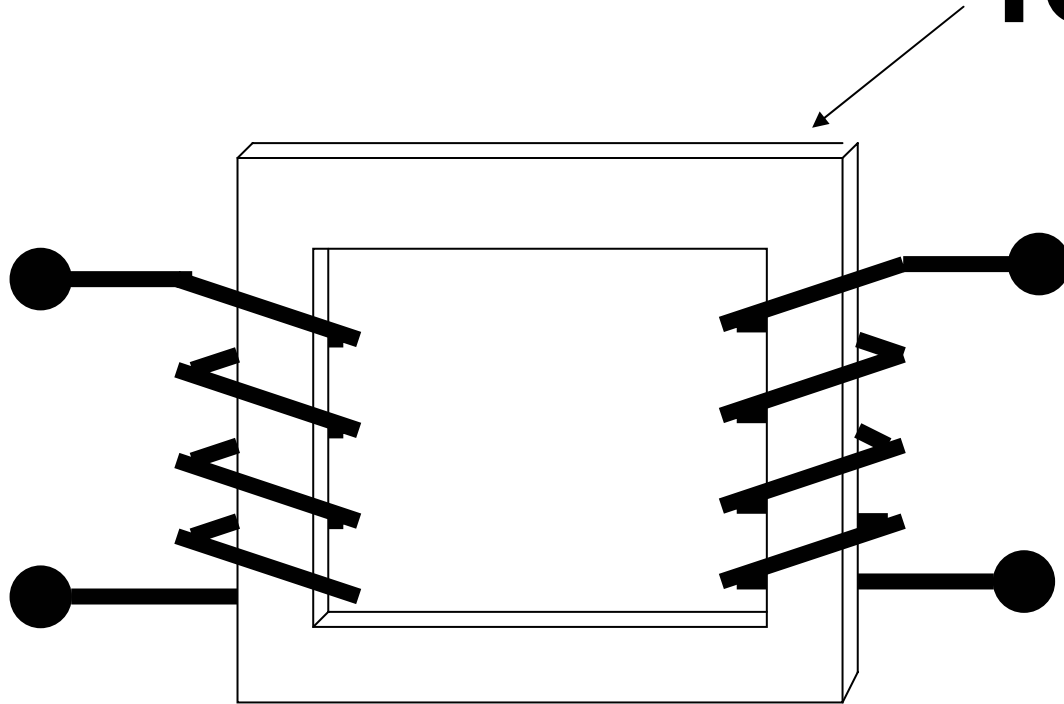


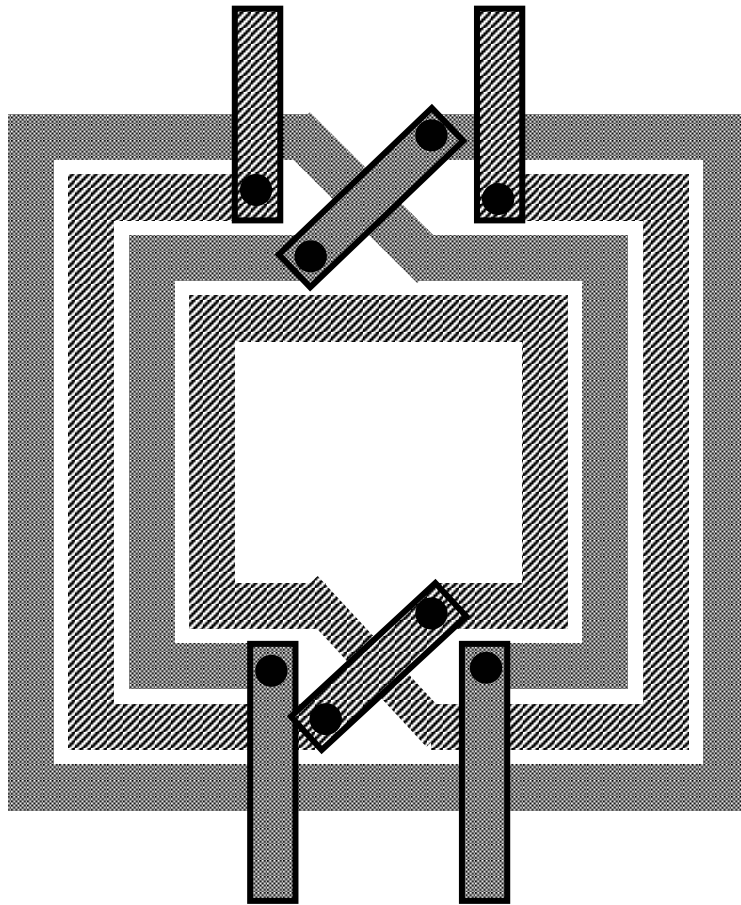
RF elements

*Philtech Inc.*

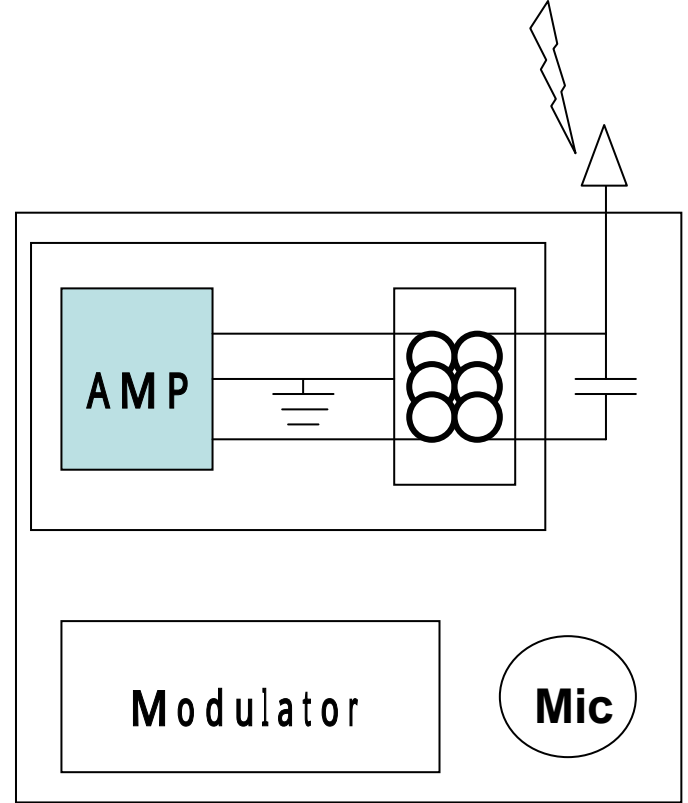


# Transformer ferrite

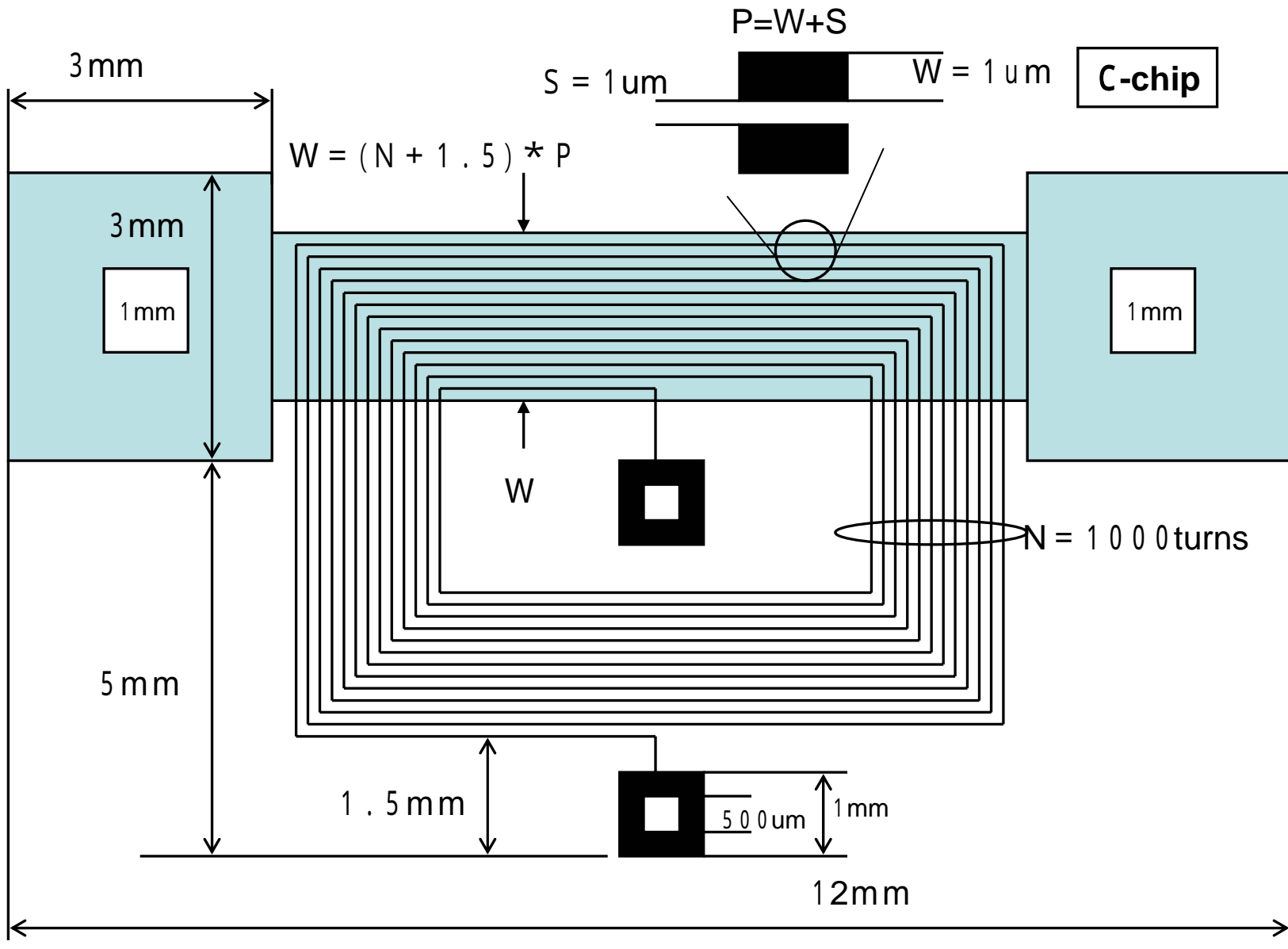


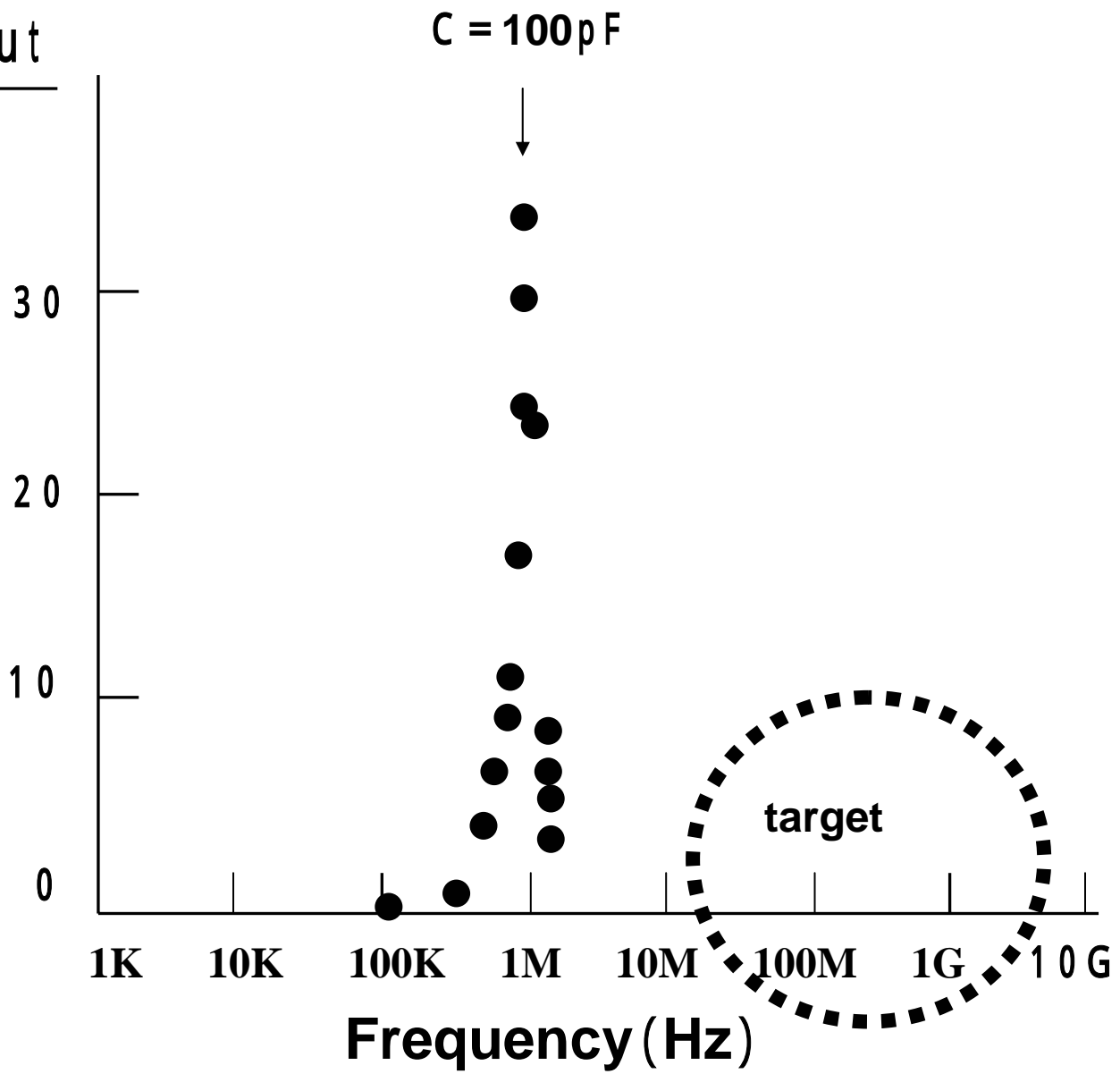
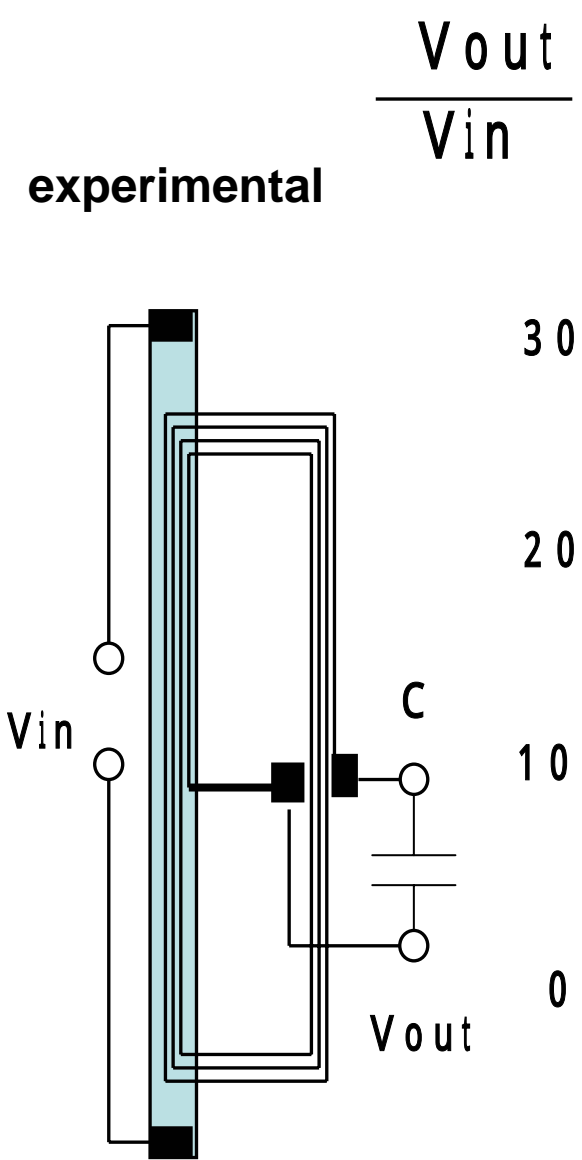


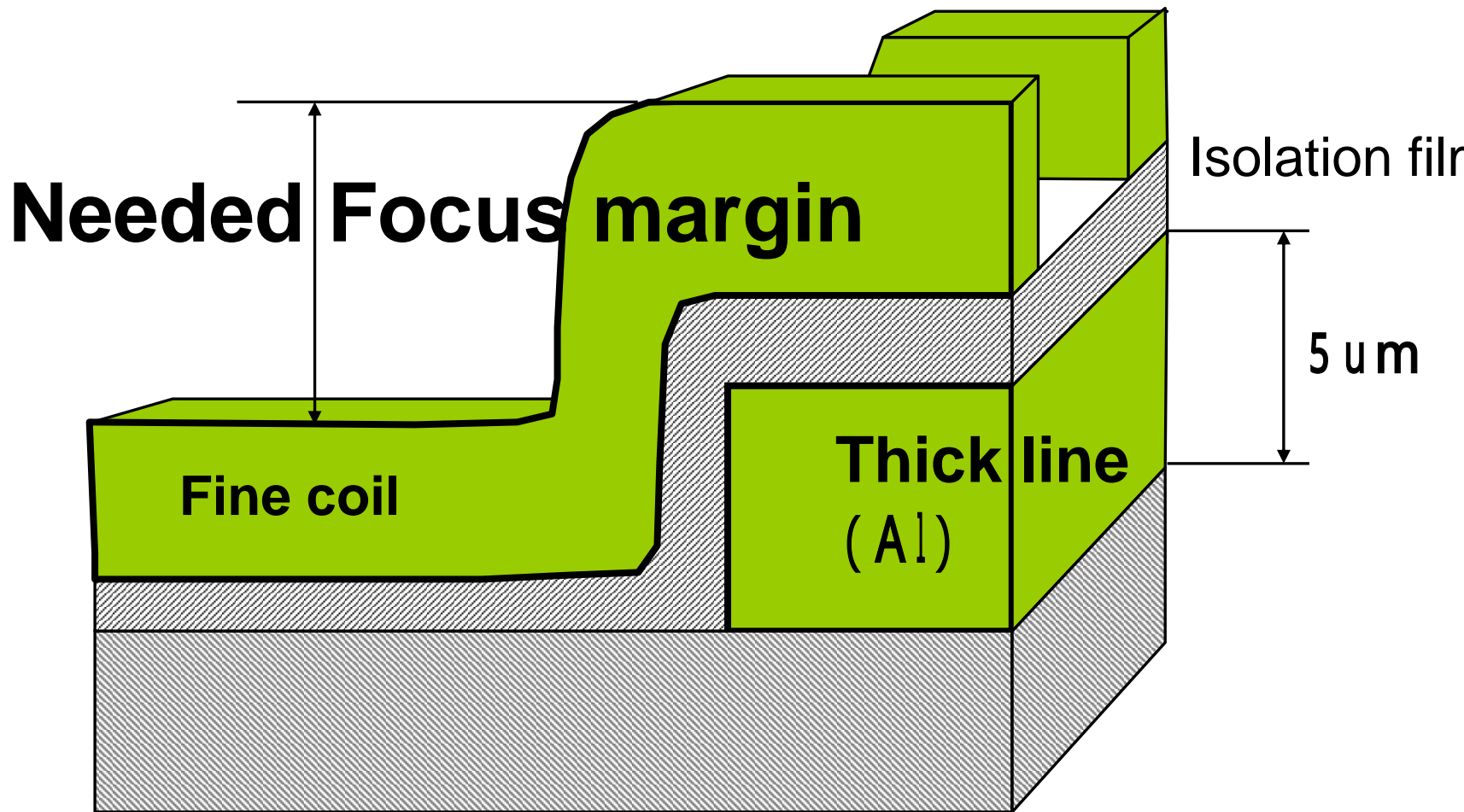
**Typical patent**



US Patent No. US6577219B2  
 Jun. 10, 2003



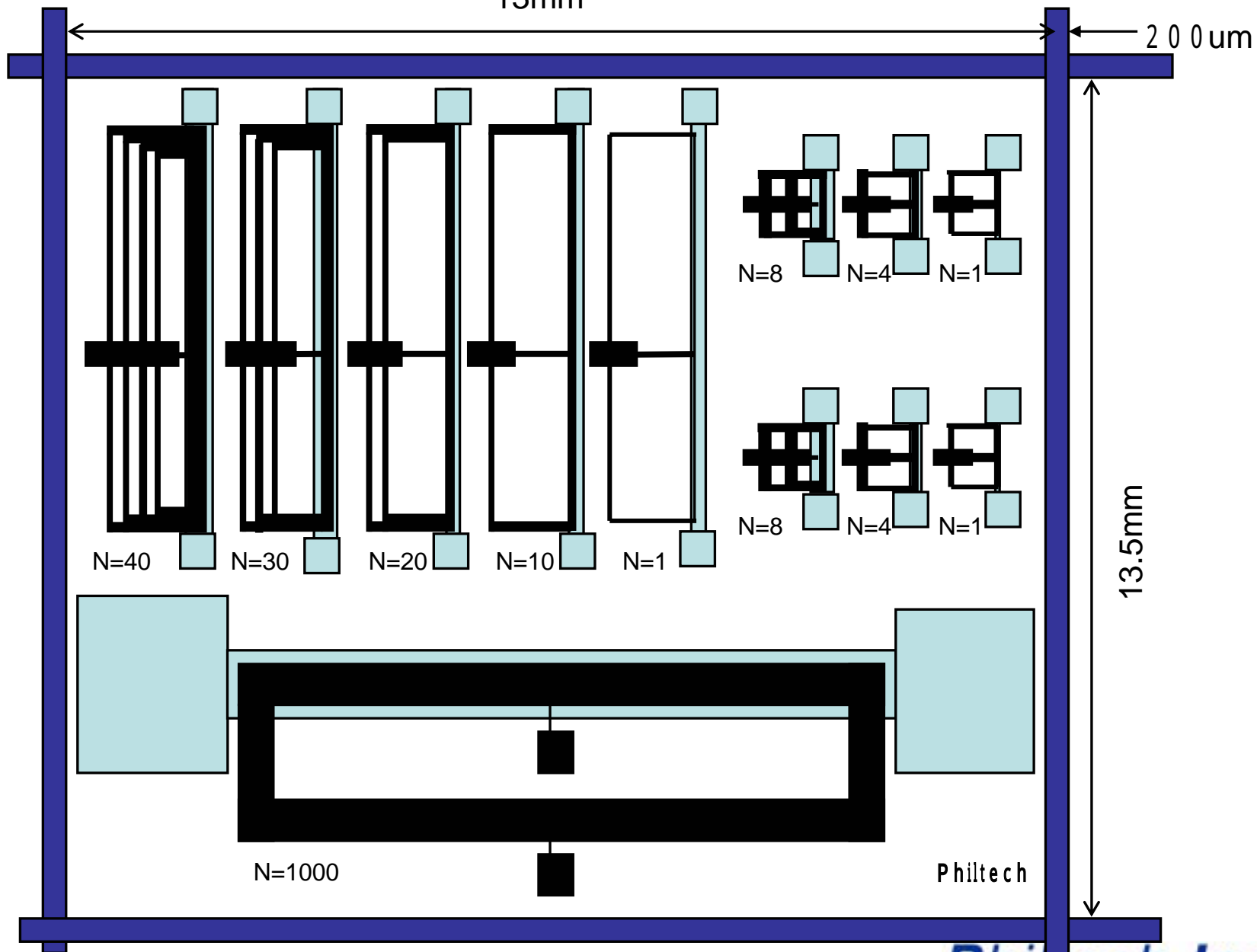




**No CMP**

13mm

200 um

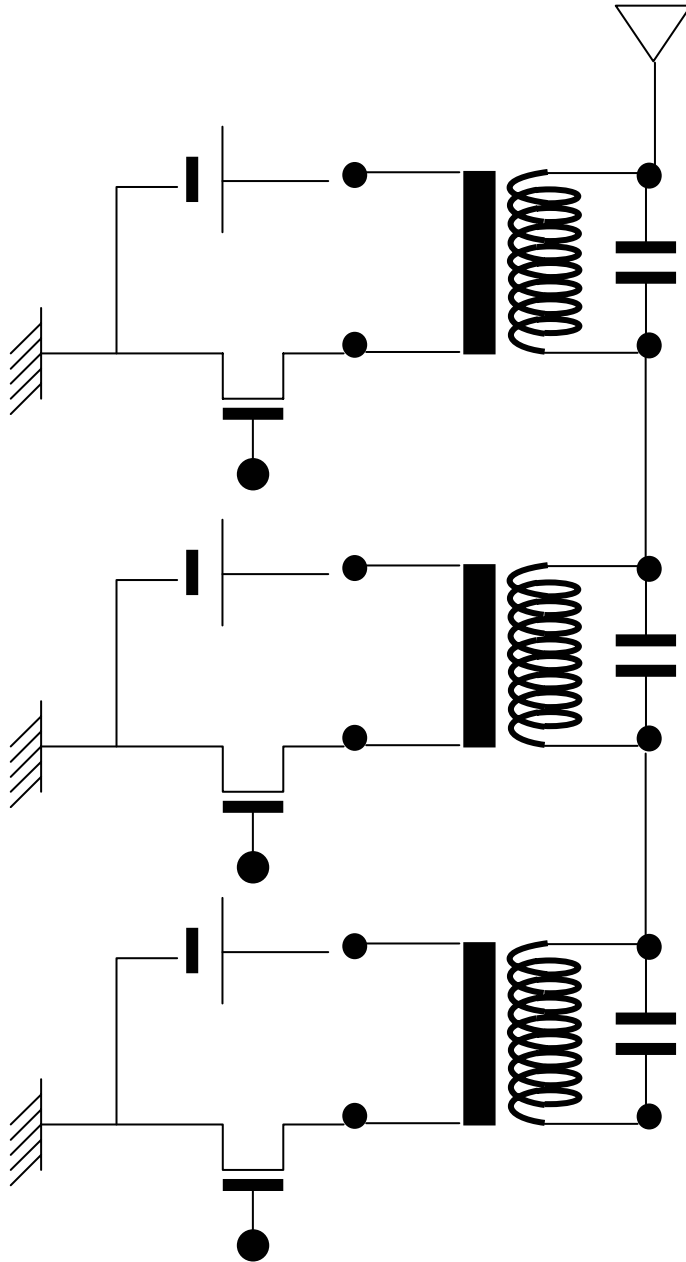


13.5mm

Philtech

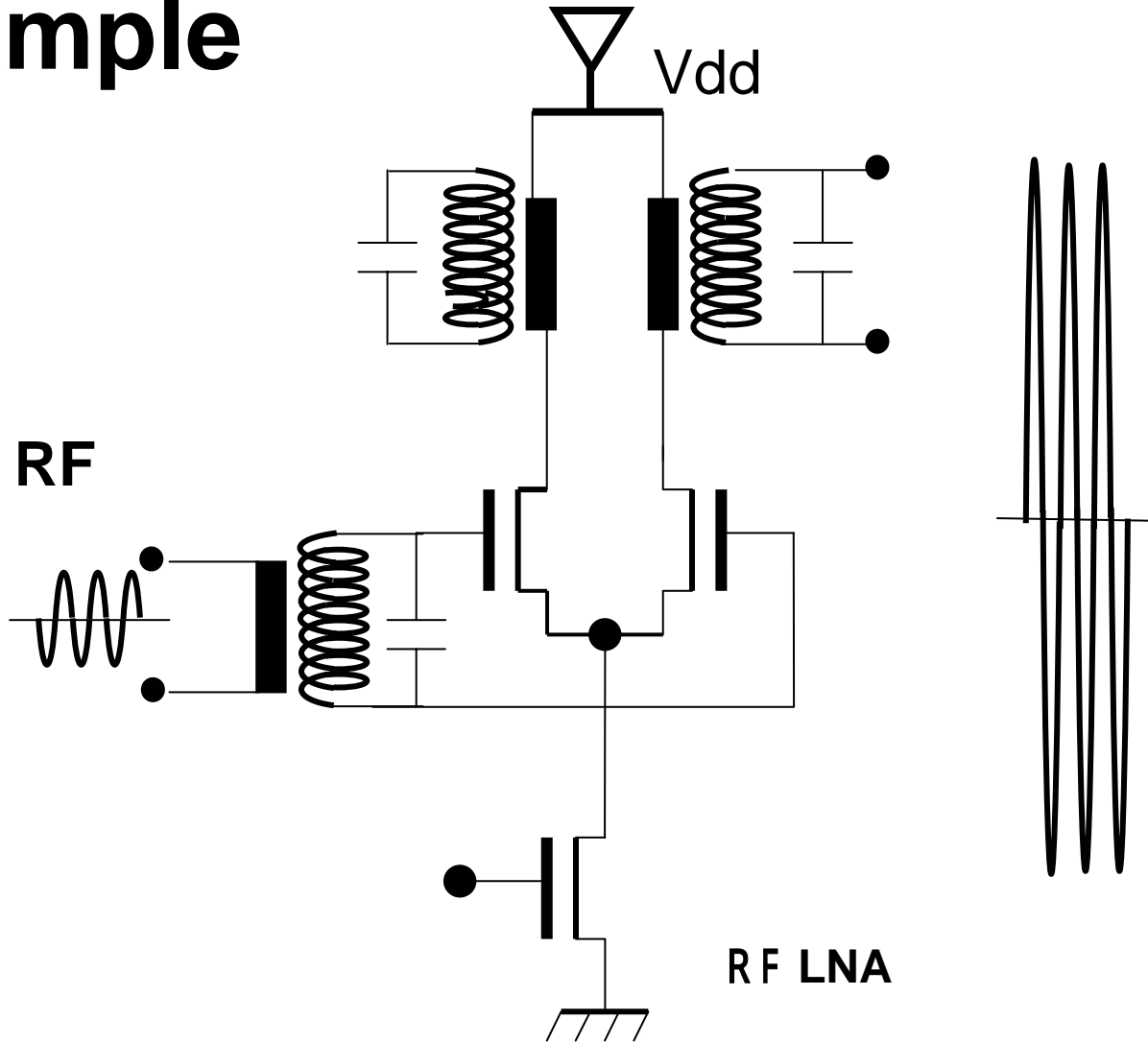
Philtech Inc.



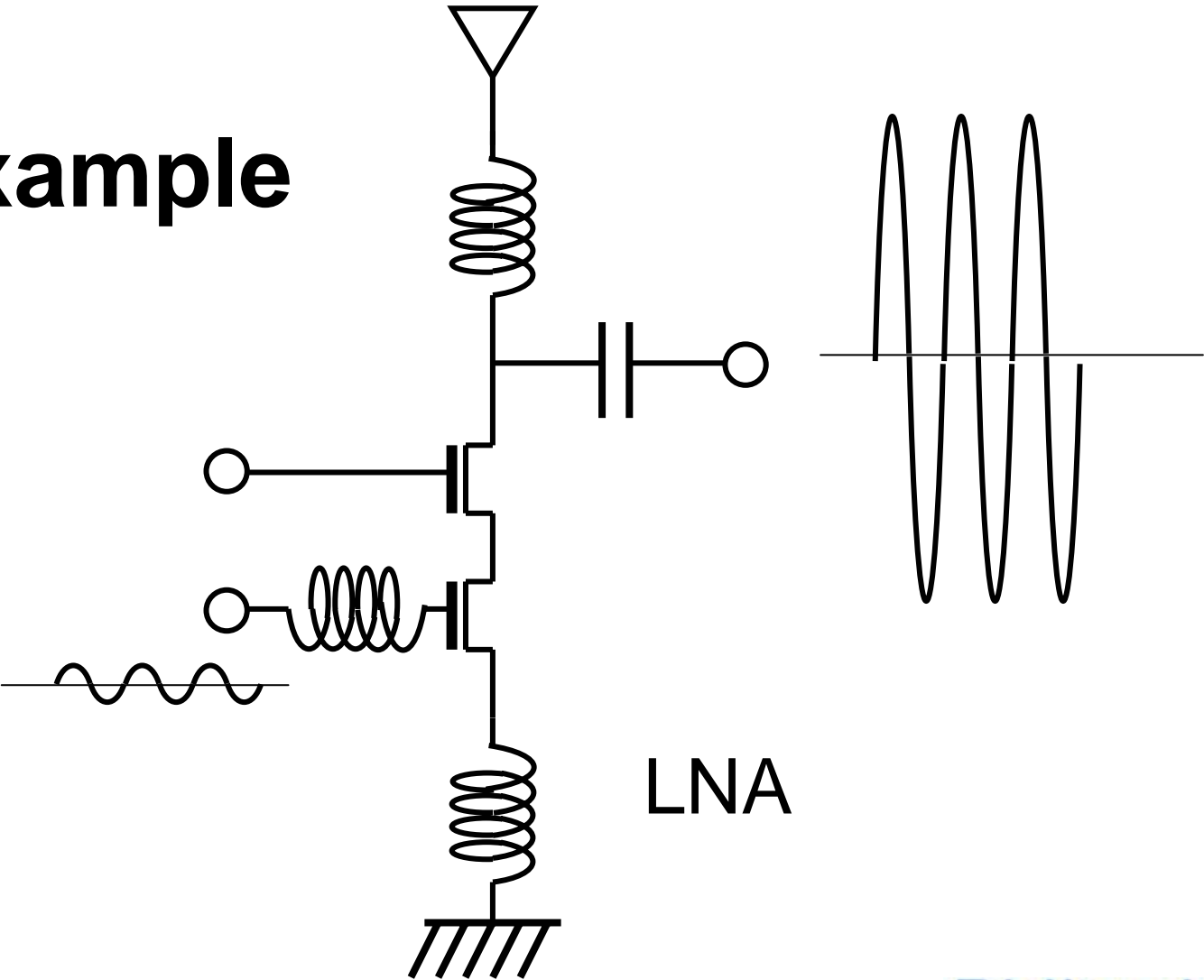


# Example

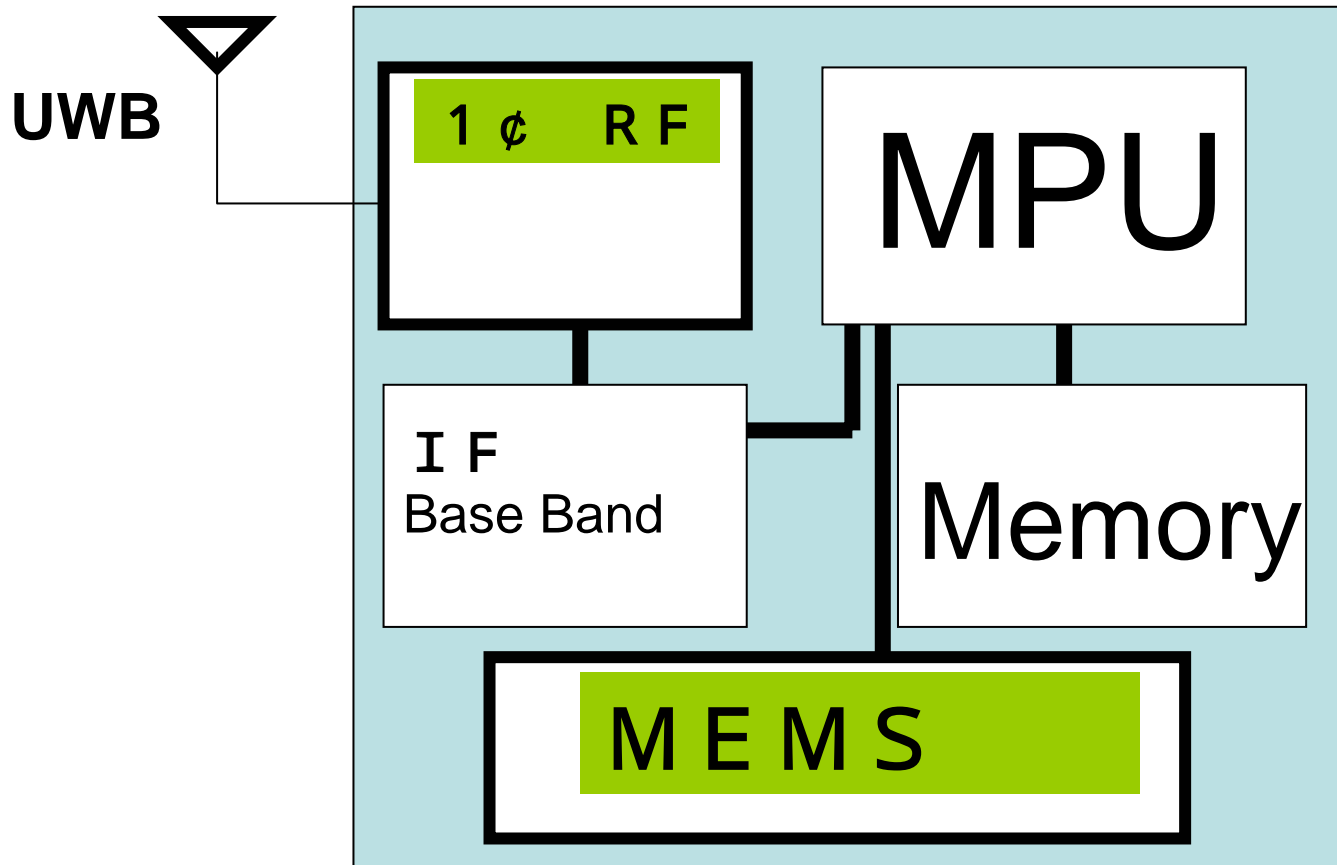
# Example



# Example

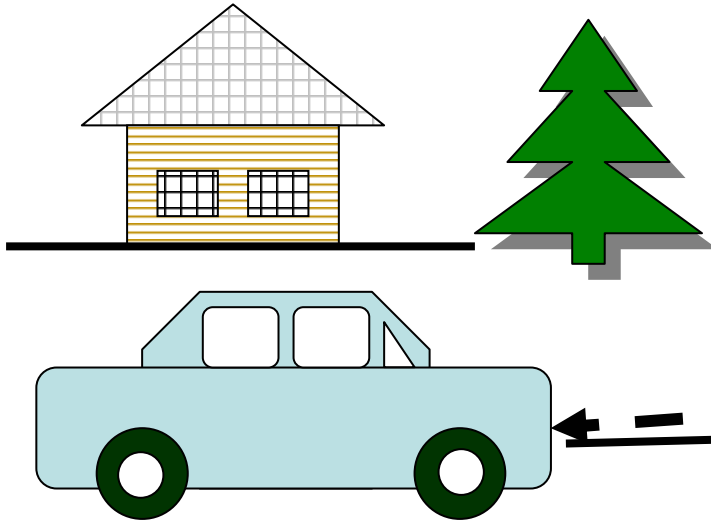


# RF-embedded L S I

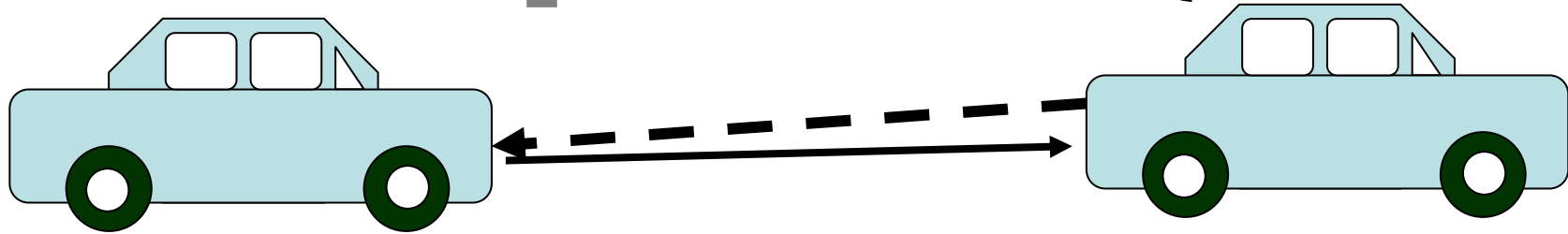


# Si RF-IC

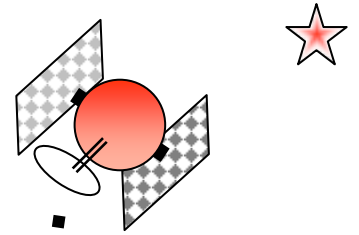
LAN



UWB



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# Growing market with RF

